AMICCOM Electronics Corporation **(The "Company")**

Company history
Date Important Chronicles

In September 2005, the company was registered and established in Taipei City, with a paid-in capital of 1 million New Taiwan Dollars.

In December 2005, the application to enter the Hsinchu Science and Industrial Park was approved, and the company was officially established. Amic Electronics valued its technology shares at 40 million NTD and raised cash capital of 79 million NTD, resulting in a paid-in capital of 120 million NTD.

In March 2006, the world's first 4X2 matrix chip A7531 for satellites, developed using CMOS technology, was released.

In March 2006, the 2.4GHz chip A7122 successfully entered the gaming controller market for PS3.

In April 2006, the 2.4GHz chip A7121 successfully entered the market for the world's first Digital Video Baby Monitor.

In November 2006, the 2.4GHz chip A7122 successfully entered the Gaming Rock Band market.

In January 2008, the satellite receiver chip A7282 successfully entered the PND market.

In June 2008, the 2.4GHz series chips successfully entered the wireless model aircraft market.

In September 2008, obtained ISO 9001:2008 quality certification.

In November 2008, the sub_1GHz series chips successfully entered the energy-saving market.

In December 2008, the 2.4GHz series chips successfully entered the computer peripheral market.

In March 2010, the sub_1GHz series chips successfully entered the automotive market.

In March 2010, the 2.4GHz series chips successfully entered the motion-sensing game market.

In March 2010, Mainland Shenzhen Representative Office was officially established.

In March 2010, Mr. San Tan, Tzeng was elected as the chairman of the company.

In May 2010, a premium capital increase was conducted, resulting in a paid-in capital amount of NT$233.82 million after the increase.

In August 2010, relocated to the Silicon Research and Development Center, No. 1, Li-Hsin Road 1, Hsinchu Science Park.

In September 2010, the sub_1GHz series chips successfully entered the wireless meter reading market.

In November 2010, the 2.4GHz series chips successfully entered the Internet of Things market.

In June 2011, the surplus was converted into capital, and after the capital increase, the paid-in capital amounted to NT$335.39 million.

In July 2011, the integrated Tone Detector satellite 2X2 matrix chip A7522 successfully entered the Japanese market.

In August 2011, the 2.4GHz standard Zigbee chip successfully entered the Internet of Things market.

In September 2011, a premium capital increase was conducted, resulting in a paid-in capital amount of NT$395.39 million after the increase.

In December 2011, Mainland Shanghai Representative Office was officially established.

In December 2011, the Securities and Futures Bureau of the Financial Supervisory Commission approved the public offering of the stock to be reissued.

In February 2012, the 2.4GHz chip A7153 received Zigbee/RF4CE certification from the Zigbee Alliance.

In February 2012, the sub_1GHz chip A7108 successfully entered the wireless smart meter market and won the 2012 China ACE Award for Best RF/Wireless Product of the Year.

In April 2012, the Salary and Compensation Committee was established.

In May 2012, the new generation 2.4GHz highly integrated RF transceiver chip A7137 was released.

In May 2012, employee bonuses were converted into capital increase and employee stock option certificates were issued for capital increase. After the increase, the paid-in capital amounted to NT$ 409.34 million.

In June 2012, registered for emerging stock market.

In January 2013, the fifth generation Single LNB satellite receiver chip A7833 was released.

In January 2013, the fifth generation 4x1 DiSEqC LNB Switch A7511 was released.

In February 2013, released the fourth generation built-in PA with a maximum output of 20dBm and a high-speed 4Mbps 2.4GHz TRx A7190.

In February 2013, released the fifth generation 4mA low receiving current sub-1GHz TRx A7129/A7139.

In May 2013, Over-the-counter stocks listed.

In June 2013, a cash capital increase was conducted before going public, resulting in a paid-in capital amount of NT$ 454.8 million.

In February 2014, the Bluetooth Low Energy series chip received Bluetooth BQB certification and announced Taiwan's first Bluetooth Low Energy chip.

In March 2014, a series of new generation highly integrated RF SoCs were released, including the wireless audio transmission A8101, Bluetooth low energy A8105, and sub-1GHz SoC A9108, further deepening the layout of the Internet of Things.

In August 2014, the new generation of highly integrated Zigbee/RF4CE wireless RF transceiver SoC chip A8153 was announced.

In August 2014, the S-band Down Converter satellite receiving chip A7837 was released.

In August 2014, the new generation of highly integrated sub-1GHz wireless RF SoC chip A9112 was announced.

In August 2014, the new generation of highly integrated sub-1GHz wireless chip A7112 was released.

In August 2014, the 2.4GHz 2Mbps wireless transceiver SoC chip A8125 was released.

In August 2014, the 2.4GHz 10dBm 2Mbps wireless transceiver SoC chip A8137 was released.

In September 2014, the 2.4GHz 500Kbps wireless transceiver SoC chip A8106 was released.

In February 2015, the A8325 2.4GHz unidirectional 2Mbps wireless transmission SoC chip was released.

In March 2015, the 2.4GHz wireless transceiver USB SoC chip A8108 was released.

In April 2015, the Bluetooth Low Energy (Bluetooth LE) wireless transceiver SoC chip A8107 was released.

In April 2015, the low-receive current sub_1GHz wireless RF SoC A9129/A9139 was announced.

In June 2015, the surplus was converted into capital, and after the capital increase, the paid-in capital amounted to NT$510.45 million.

In August 2015, the A7196 wireless RF transceiver chip with a built-in 19.5dBm PA and high-speed 6Mbps 2.4GHz FSK was launched.

In August 2015, the Bluetooth Low Energy (Bluetooth LE) SiP chip A8107 SiP was released.

In August 2015, the RF IC A7216/A7316 for 2.4GHz wireless remote control toy cars was released.

In August 2015, the highly integrated 2.4GHz wireless voice SoC chip A8100 was released.

In August 2015, new shares with restricted employee rights were issued, resulting in a paid-in capital of NT$520.45 million.

In September 2015, a new generation of integrated high-precision ADC wireless sub-1GHz RF SoC A9109 was announced.

In September 2015, the new generation 4x4 integrated LNB SWITCH chip A7544 was launched.

In November 2015, released the LCD display wireless SoC series A8525/A8526.

In January 2016, a new product line of 5.8GHz wireless RF transceiver chip A5130 was launched.

In January 2016, the sub_1GHz DSSS spread spectrum wireless transceiver chip A7159 was launched.

In January 2016, a premium capital increase was conducted, resulting in a paid-in capital amount of NT$580.19 million after the increase.

In March 2016, A8107 SiP received the Greater China IC Design Achievement Award for the year 2016.

In August 2016, the new 5.8GHz wireless RF transceiver chip A5125 was released.

In August 2016, the new generation 2x4 integrated LNB SWITCH chip A7524 was launched.

In September 2016, the new generation of built-in ARM® Cortex®-M0 Bluetooth Low Energy (Bluetooth LE) SoC chip A8107M0 was announced.

In October 2016, the new generation of highly integrated sub_1GHz wireless voice SoC series chip A9101 was released.

In October 2016, the new generation of highly integrated 2.4GHz wireless audio SoC chip A8102 was released.

In December 2016, the DSSS spread spectrum modulation sub-1GHz wireless RF SoC chip A9159 was released.

In March 2017, the BLE chip series A8507/A8508 with LCD display functionality was released.

In March 2017, released the sub_1GHz A9508 with LCD display functionality.

In March 2017, the new generation of high-isolation 4x2 LNB SWITCH chips A7540/A7539 was launched.

In March 2017, the 5.8GHz wireless chip A5130/A5125 received the Achievement Award from the Greater China IC Design Company for the year: Best RF Wireless IC of the Year.

In June 2017, a new generation 13dBm 2.4GHz 2Mbps wireless transceiver SoC chip A8137M0 was released.

In September 2017, relocated to the Taiyuan Technology Park in Zhubei City, Hsinchu County.

In March 2018, the Bluetooth Low Energy (Bluetooth LE) SoC chip A8115 was released.

In May 2018, the Bluetooth Low Energy (Bluetooth LE) Mesh / BLE Central SoC chip A3107M0 was released.

In May 2018, the new generation of highly integrated Bluetooth Low Energy (Bluetooth LE) SoC series chips A3113, A3512, and A3513 was announced.

In January 2019, the Bluetooth Low Energy (Bluetooth LE) Mesh/BLE Central SoC chip A3117M0 was released.

In January 2019, the 5.8GHz wireless transceiver SoC chip A1011 was released.

In January 2019, the 2.4GHz wireless transceiver SoC chip A8125M0 was released.

In January 2019, the new generation sub_1GHz wireless transceiver chip A7136 was released.

In August 2019, the new generation sub_1GHz wireless transceiver chip A7169 was released.

In September 2019, the new generation 5.8GHz wireless RF transceiver chip A5133 was released.

In March 2020, the sub_1GHz DSSS spread spectrum wireless transceiver chip A7119 was released.

In June 2020, the sub_1GHz wireless unidirectional receiving chips A7209/A7229 were released.

In June 2020, the A7157 wireless transceiver chip with DSSS spread spectrum function at 2.4GHz was launched.

In June 2020, the Audit Committee was established.

In July 2021, the sub_1GHz wireless transmission SoC chip A9339 was released.

In December 2021, the 2.4GHz wireless transceiver chip A7157 won the 2021 EDN Asia Best Choice Award: Most Promising RF Wireless IC of the Year.

In March 2022, the 2.4GHz wireless transceiver SoC chip A8131M0 was released.

In March 2022, the low-receive current sub-1GHz wireless transceiver SoC chips A9129F6/A9139F6/A9159F6 were released.

In December 2022, the 2.4GHz wireless transceiver SoC chip A8131M0 won the EDN Asia Golden Selection Award for the year: Best RF Wireless IC.

In October 2023, the sub_1GHz low current consumption wireless transceiver SOC chip A9129M0 was released.

In November 2023, the A7149 sub-1GHz wireless transceiver chip with a super low receiving current of 1.65mA was released.

In December 2023, the Sub_1GHz wireless transceiver chip A7149 won the 2023 EDN Asia Innovation Award: Best RF Wireless IC of the Year.

In January 2024, the A7136 sub-1GHz RF chip successfully passed the WiSUN Association certification and obtained the WiSUN FAN 1.0 certification.

In March 2024, A9146M4 (SoC) has passed WiSUN FAN 1.0 certification, providing exceptional performance and laying the foundation for development efficiency.

In May 2024, the company made its debut at the WIRELESS JAPAN x WTP exhibition, showcasing its latest low-power RF chips and Wi-SUN technology, attracting the attention of many industry players.

In July 2024, A9146M4 successfully passed Wi-SUN FAN v1.0 (Router) and (Border Router) certification.